

TQFP/QFN/MLF Package

TEST RESULTS

INDUCTANCE (nH)

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SCOPE

To perform Inductance and Capacitance testing on Electrical socket contacts as manufactured and submitted by the test sponsor.

APPLICABLE DOCUMENTS

Standards:

MIL-STD-1344

EIA Publication 364

TEST SAMPLES AND PREPARATION

1. The following test samples were submitted by the test sponsor for the evaluation to be performed by Contech Research, Inc.

5, Mounted contacts, P/N SMSP1001
10, Loose contacts
2. The following additional materials were submitted by the test sponsor to assist and perform the testing of items listed in #1 above.

1, Contact holding block
4, Test boards
3. Test boards for mounting test samples were supplied by the test sponsor.
4. The test samples were not cleaned prior to testing.
5. Unless otherwise specified in the test procedures used, no further preparation was used.

PROJECT NO.: 99360

SPECIFICATIONS: EIA-364

PART NO.: SMSP1001

PART DESCRIPTION: Socket Contacts

SAMPLE SIZE: 5 Contacts

TECHNICIAN: MO

START DATE: 6/10/99

COMPLETE DATE: 6/11/99

ROOM AMBIENT: 22°C

RELATIVE HUMIDITY: 40%

EQUIPMENT ID#: 757

INDUCTANCE

PURPOSE:

To determine the (mutual or self) inductance characteristics of the contact system under evaluation.

PROCEDURE:

1. The test was performed in accordance with EIA 364, TP 69.
2. Test Conditions:
 - Test Frequency : 500 MHz
 - Type of Inductance : Self
 - Mounting Conditions : Unmounted
 - No. of Measurements : 5
3. Contacts were tested outside the socket bodies.
4. The inductance analyzer was calibrated with the test fixture in place, but without the test sample.
5. The sample was placed in the inductance analyzer test fixture and the inductance was measured and recorded.

REQUIREMENTS:

The inductance shall be measured and recorded.

RESULTS:

The following is the data observed:

INDUCTANCE (nH)

3.1
3.2
3.1
3.3
3.2